



News Release

Kuala Lumpur, 9 August 2012 – Unisem (M) Berhad today announced results for the second quarter ended 30 June 2012 (**2Q12**).

The Group recorded revenue of RM282.9 million (approx. US\$91.6 million) for 2Q12, 8 percent decline from RM307.5 million (approx. US\$101.9 million) achieved in the same quarter a year ago (**2Q11**). For 2Q12, the Group recorded a net loss of RM7.8 million (approx. US\$2.5 million) compared to a net profit of RM11.9 million (approx. US\$3.9 million) in 2Q11.

Compared to the preceding quarter (**1Q12**) Group revenue grew 10.3 percent from RM256.6 million (approx. US\$83.6 million) and net loss decreased 43.3 percent from net loss of RM13.7 million (approx. US\$4.4 million) in 1Q12.

For the first half of the current financial year ended 30 June 2012 (**1H12**), the Group recorded revenue of RM539.5 million (approx. US\$175.2 million), a 10 percent decline from RM599.5 million (approx. US\$197.5 million) achieved for the six-month period a year ago (**1H11**). For 1H12, the Group recorded a net loss of RM21.4 million (approx. US\$7.0 million) compared to net profit of RM17.3 million (approx. US\$5.7 million) achieved in 1H11.

The decline in revenue and net profit was principally attributable to declined sales revenue, lower selling price arising from change in product mix, lower foreign exchange gains and higher depreciation charges.

Group earnings before interest, tax, depreciation and amortization (**EBITDA**) for 2Q12 came in at about RM39.5 million (approx. US\$12.8 million), EBITDA margin was about 14 percent. Equipment capacity utilization averaged at about 62 percent for the group in 2Q12. Group capital expenditure incurred in 2Q12 was about RM33.1 million (approx. US\$10.7 million), principally for purchase of equipment for advanced packaging activities for Unisem (M) Berhad and Unisem Chengdu.

Commenting on the outlook of the Group, Mr. John Chia Sin Tet, group managing director said, "Sentiment in the semiconductor industry has deteriorated in recent months due to uncertainty and bearishness in the global economy particularly in Europe. The operating environment is expected to remain challenging for the remaining period till the end of the financial year. The initiatives taken by the Group to right size our headcount and tweak our package portfolio will continue and we expect to incur some costs associated with the implementation of this new business model in the next few quarters. We believe the new business model will progressively improve the profitability and sustainability of the Group going forward."

About Unisem

Unisem is a global provider of semiconductor assembly and test services for many of the world's most successful electronics companies. Unisem offers an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding, a wide range of leadframe and substrate IC packaging, wafer level CSP and RF, analog, digital and mixed-signal test services. Our turnkey services include design, assembly, test, failure analysis, and electrical and thermal characterization. With approximately 9,500 employees worldwide, Unisem has factory locations in Ipoh, Malaysia; Wales, United Kingdom; Chengdu, People's Republic of China; Batam, Indonesia and Sunnyvale, USA. The company is headquartered in Kuala Lumpur, Malaysia. For more information about the company, its products and services, please visit its website at www.unisemgroup.com.